



AIP31086

80CH COMMON / SEGMENT DRIVER FOR DOT MATRIX LCD

1、GENERAL DESCRIPTION

The AIP31086 is an LCD driver LSI which is fabricated by low power CMOS high voltage process technology. In segment driver mode, it can be interfaced in 1-bit serial or 4-bit parallel method by the controller. In common driver mode, dual type mode is applicable. And in segment mode application, the power down function reduces power consumption.

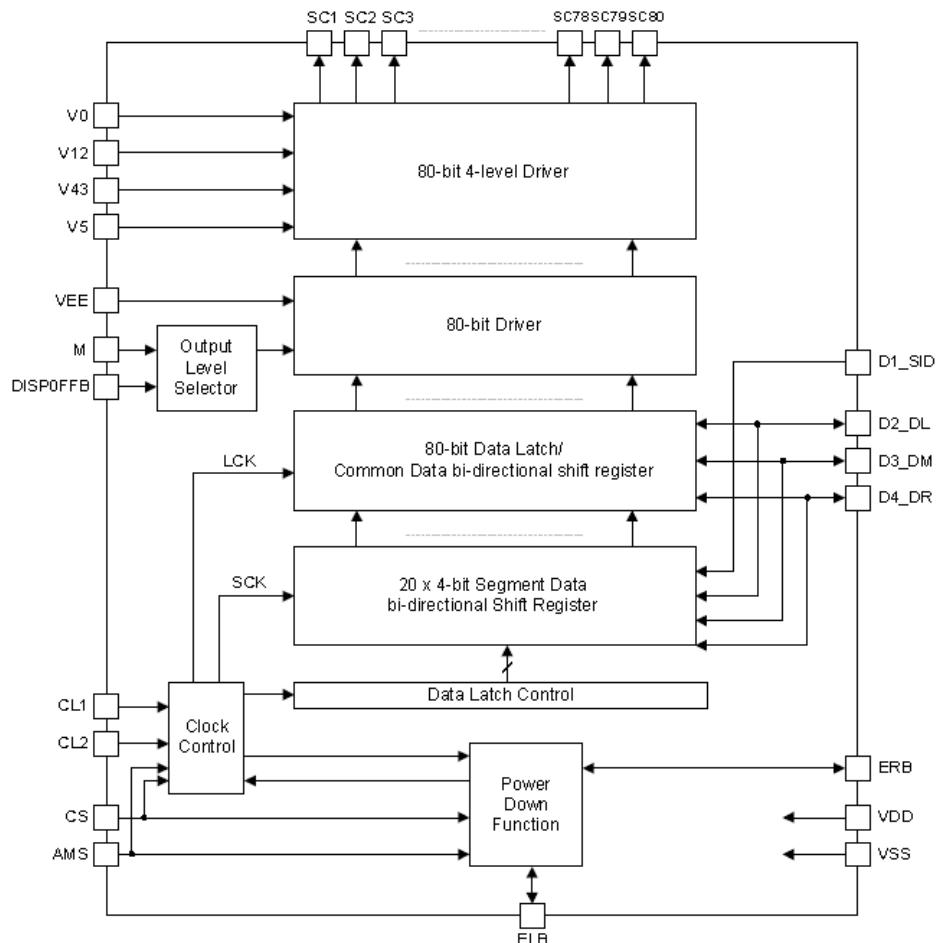
Features

- Power supply voltage: 3V~5V
- Supply voltage for display: 6 to 28V (VDD-VEE)
- 4-bit parallel / 1-bit serial data processing (in segment mode)
- Single mode operation / dual mode operation (in common mode)
- Power down function (in segment mode)
- Applicable LCD duty: 1/64 – 1/256
- 5V/30V High voltage CMOS process
- Chip size: 3250×3160 ($\mu\text{m} \times \mu\text{m}$)
- The IC substrate should be connected to VDD or float in the PCB layout artwork.
- LQFP100 or bare chip available



2、BLOCK DIAGRAM AND BLOCK DESCRIPTION

2.1、BLOCK DIAGRAM





2.2、BLOCK DESCRIPTION

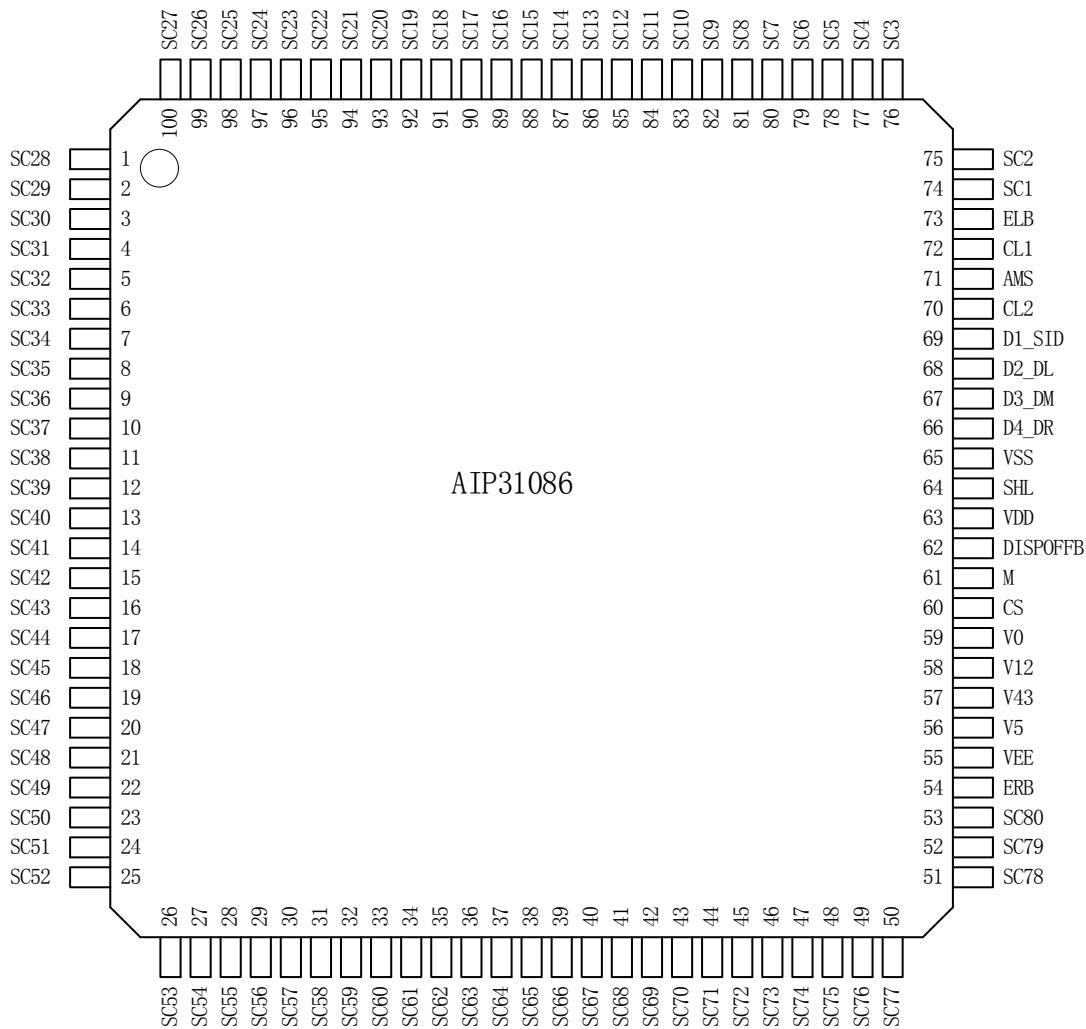
Name	Function	COM /SEG
Clock control	Generates latch clock (LCK), shift clock (SCK) and control clock timing according to the input of CL1, CL2 and control inputs (CS, AMS). In common driver application mode, this block generates the shift clock (LCK) for the common data Bi-directional shift register.	COM /SEG
Data latch control	Determines the direction of segment data shift, and input data of each Bi-directional shift register. In 4-bit segment data parallel transfer mode, data is shifted by a 4-bit unit. In common driver application mode, data is transferred to the common data shift register directly, which disables this block.	SEG
Power down function	Controls the clock enable state of the current driver according to the input value of enable pin (ELB or ERB). If enable input value is “Low”, every clock of the current driver is enabled and the clock control block works. But if enable input is “High”, current driver is disabled and the input data value has no effect on the output level. So power consumption can be lowered.	SEG
Output level selector	Controls the output voltage level according to the input control pin (M and DISPOFFB) (refer to PIN DESCRIPTION).	COM /SEG
20x4-bit segment data I-directional shift register	Stores output data value by shifting the input values. In 1-bit serial interface mode application, all 80 shift clocks (SCK) are needed to store all the display data. But in 4-bit parallel transfer mode application, only 20 clocks are needed. In common driver application mode, this block does not work.	SEG
80-bit data latch / common data I-directional shift register	In segment driver application mode, the data from the 20x4-bit segment data shift register are latched for segment driver output. In single-type common driver application, 1-bit input data (from DL or DR pin) is shifted and latched by the direction according to the SHL signal input. In dual-type common application mode, 80-bit registers are divided by two blocks and controlled independently (refer to NOTE 3).	COM /SEG
80-bit level shifter	Voltage level shifter block for high voltage part. The inputs of this block are of logical voltage level and the outputs of this block are at high voltage level value. These values are input in to the driver.	SEG
80-bit 4-level driver	Selects the output voltage level according to M and latched data value. If the data value is "High" the driver output is at selected voltage level (V0 or V5), and in the reverse case the driver output value is at the non-selected level (V12 or V43). In segment driver application mode, non-selected output value is V2 or V3. and when in common driver application, this value becomes V1 or V4.	SEG



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2.3 PIN CONFIGURATIONS

LQFP100



2.4、PIN DESCRIPTION

Pin No.	Pin Name	I/O	Description	Interface
63	VDD	Power supply	Logical "High" input port (+5V 10%, +3V 10%)	Power
65	VSS		0V (GND)	
55	VEE		Logical "Low" for high voltage part	
59 58 57 56	V0, V12, V43, V5	LCD driver output voltage level	Bias supply voltage input to drive the LCD. Bias voltage divided by the resistance is usually used as a supply voltage source (refer to NOTE 2).	Power



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1~53 74~ 100	SC1 - SC80	LCD driver output	O	Display data output pin which corresponds to the respective latch contents. One of V0, V12, V34 and V5 is selected as a display driving voltage source according to the combination of the latched data level and M signal (refer to NOTE 1).	LCD															
70	CL2	Data shift clock	I	Clock pulse input for the bi-directional shift register. – In segment driver application mode, the data is shifted to 20 x 4-bit segment data shift. The clock pulse, which was input when the enable bit (ELB/ERB) is in not active condition, is invalid. – In common driver application mode, the data is shifted to 80-bit common data bi-directional shift register by the CL1 clock. Hence, this clock pin is not used (Open or connect this pin to VDD).	Controller															
61	M	AC signal for LCD driver output	I	Alternate signal input pin for LCD driving. Normal frame inversion signal is input in to this pin.	Controller															
72	CL1	Data latch clock	I	– In segment driver application mode, this signal is used for latching the shift register contents at the falling edge of this clock pulse. CL1 pulse "High" level initializes power-down function block. – In common driver application mode, CL1 is used as a shifting clock of common output data.	Controller															
62	DISPOF FB	Display OFF control	I	Control input pin to fix the driver output (SC1~SC80) to V0 level, during "Low" value input. LCD becomes non-selected by V0 level output from every output of segment drivers and every output of common drivers.	Controller															
60	CS	COM / SEG mode control	I	When CS = "Low", AIP31086 is used as an 80-bit segment driver. When CS = "High", AIP31086 is set to an 80-bit common driver	VDD / VSS															
71	AMS	Applicatio n Mode select	I	According to the input value of the AMS and the CS pin, application mode of AIP31086 is differs as shown below. <table border="1"><thead><tr><th>C S</th><th>A M S</th><th>Application Mode</th><th>COM/SE G</th></tr></thead><tbody><tr><td>0</td><td>0</td><td>4-bit parallel interface mode</td><td rowspan="2"></td></tr><tr><td>0</td><td>1</td><td>1-bit serial interface mode</td></tr><tr><td>1</td><td>0</td><td>Single type application mode</td><td>COM</td></tr></tbody></table>	C S	A M S	Application Mode	COM/SE G	0	0	4-bit parallel interface mode		0	1	1-bit serial interface mode	1	0	Single type application mode	COM	VDD / VSS
C S	A M S	Application Mode	COM/SE G																	
0	0	4-bit parallel interface mode																		
0	1	1-bit serial interface mode																		
1	0	Single type application mode	COM																	



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				1	1	Dual type application mode										
69 68 67 66	D1_SID, D2_DL, D3_DM, D4_DR	Display data input / serial input data / left, right data input output	I/O	In segment driver application mode, these pins are used as 4-bit data input pin (when 4-bit parallel interface mode : AMS = "Low"), or D1_SID is used as serial data input pin and other pins are not used (connect these to VDD) (when 1-bit serial interface mode : AMS = "High"). In common driver application mode, the data is shifted from D2_DL(D4_DR) to D4_DR(D2_DL), when in single type interface mode (AMS = "Low"). In dual-type application case, the data are shifted from D2_DL and D3_DM (D4_DR and D3_DM) to D4_DR(D2_DL). In each case the direction of the data shift and the connection of data pins are determined by SHL input (refer to NOTE 3, NOTE 4).	Controller											
64	SHL	Shift direction control	I	When SHL = "Low", data is shifted from left to right. When SHL = "High", the direction is reversed. (refer to NOTE3)	VDD/VSS											
73 54	ELB ERB	Enable data Input/output	I/O	In segment driver application mode, the internal operation is enabled only when enable input (ELB or ERB) is "Low" (power down function). When several drivers are serially connected, the enable state of each driver is shifted according to the SHL input. Connect these pins as below. <table border="1"><thead><tr><th rowspan="2">SHL</th><th colspan="2">Segment Driver</th></tr><tr><th>ELB</th><th>ERB</th></tr></thead><tbody><tr><td>L</td><td>Output(open)</td><td>Input(VSS)</td></tr><tr><td>H</td><td>Input(VSS)</td><td>Output(open)</td></tr></tbody></table> In common driver application mode, power down function is not used. Open these pins.	SHL	Segment Driver		ELB	ERB	L	Output(open)	Input(VSS)	H	Input(VSS)	Output(open)	
SHL	Segment Driver															
	ELB	ERB														
L	Output(open)	Input(VSS)														
H	Input(VSS)	Output(open)														

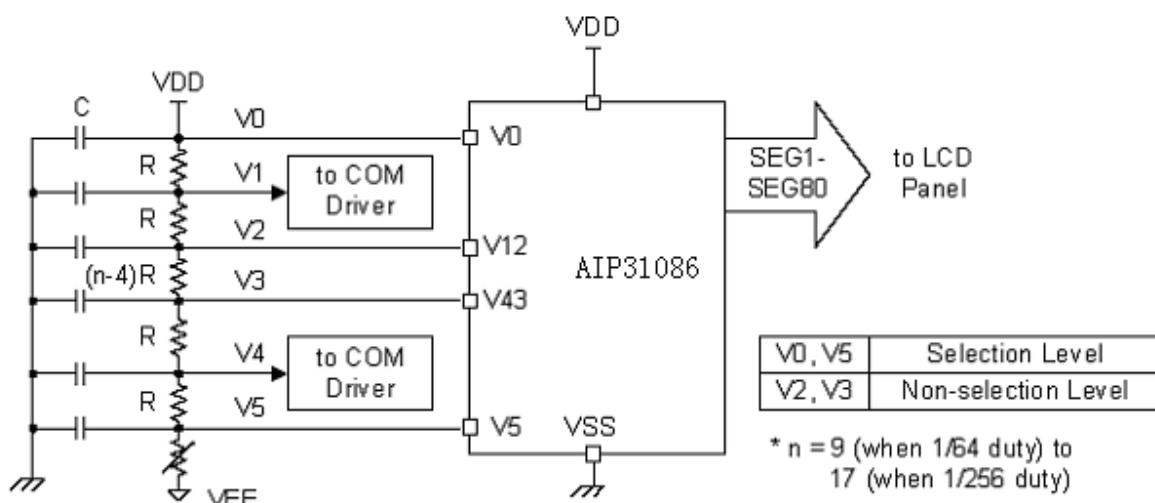


NOTE 1. Output Level Control

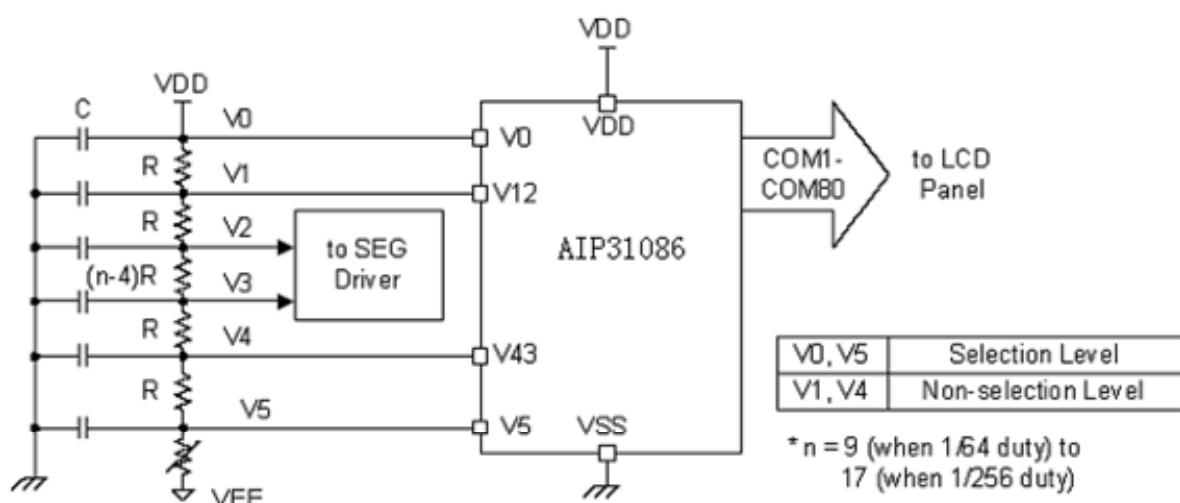
M	Latched data	DISPOFFB	Output level (SC1 –SC80)	
			SEG Mode	COM Mode
L	L	H	V12 (V2)	V12 (V1)
L	H	H	V0	V5
H	L	H	V43 (V3)	V43 (V4)
H	H	H	V5	V0
X	X	L	V0	V0

NOTE 2. LCD Driving Voltage Application Circuit

(1) Segment driver application (CS = “Low”)



(2) Common driver application (CS = “High”)





NOTE 3. Data Shift Direction according to Control Signals

(1) When CS = "Low" (segment driver application)

AMS	SHL	Application mode	Data Direction	Input Pin
L	L	4-Bit Parallel Data Transfer Mode (SEG)	<p>Diagram illustrating 4-bit parallel data transfer mode (SEG). The top part shows a shift direction from right to left, where the first data (D1) is shifted out and the last data (D4) is shifted in. The bottom part shows a shift direction from left to right, where the first data (D1) is shifted in and the last data (D4) is shifted out.</p> <p>Shift direction: Right (top) / Left (bottom)</p> <p>first data: D1 (top), D4 (bottom)</p> <p>last data: D4 (top), D1 (bottom)</p>	D1_SID, D2_DL, D3_DM, D4_DR
			<p>Diagram illustrating 1-bit serial data transfer mode (SEG). The top part shows a shift direction from right to left, where the first data (D1_SID) is shifted out and the last data (D1_SID) is shifted in. The bottom part shows a shift direction from left to right, where the first data (D1_SID) is shifted in and the last data (D1_SID) is shifted out.</p> <p>Shift direction: Right (top) / Left (bottom)</p> <p>first data: D1_SID (top), D1_SID (bottom)</p> <p>last data: D1_SID (top), D1_SID (bottom)</p>	D1_SID
H	H	1-Bit Serial Data Transfer Mode (SEG)	<p>Diagram illustrating 4-bit parallel data transfer mode (SEG). The top part shows a shift direction from right to left, where the first data (D1) is shifted out and the last data (D4) is shifted in. The bottom part shows a shift direction from left to right, where the first data (D1) is shifted in and the last data (D4) is shifted out.</p> <p>Shift direction: Right (top) / Left (bottom)</p> <p>first data: D1 (top), D4 (bottom)</p> <p>last data: D4 (top), D1 (bottom)</p>	
			<p>Diagram illustrating 1-bit serial data transfer mode (SEG). The top part shows a shift direction from right to left, where the first data (D1_SID) is shifted out and the last data (D1_SID) is shifted in. The bottom part shows a shift direction from left to right, where the first data (D1_SID) is shifted in and the last data (D1_SID) is shifted out.</p> <p>Shift direction: Right (top) / Left (bottom)</p> <p>first data: D1_SID (top), D1_SID (bottom)</p> <p>last data: D1_SID (top), D1_SID (bottom)</p>	



(2) When CS = "High" (common driver application)

AMS	SHL	Application mode	Data Direction	Input Pin
L	L	Single-type Application Mode (COM)	 Input Data (D2_DL) → Stage 1 → Stage 2 → Stage 3 → Output Data (D4_DR)	D2_DL
	H		 Output Data (D2_DL) ← Stage 1 ← Stage 2 ← Stage 3 ← Input Data (D2_DR)	D4_DR
H	L	Dual-type Application Mode (COM)	 Input Data 1 (D2_DL) → Stage 1 → Stage 2 → Stage 3 → Output Data (D4_DR) Input Data 2 (D3_DM) → Stage 1 → Stage 2 → Stage 3 → Output Data (D4_DR) Output Data (D2_DL) ← Stage 1 ← Stage 2 ← Stage 3 ← Input Data 1 (D2_DR)	D2_DL, D3_DM
	H		 Output Data (D2_DL) ← Stage 1 ← Stage 2 ← Stage 3 ← Input Data 2 (D3_DM) Input Data 2 (D3_DM) → Stage 1 → Stage 2 → Stage 3 → Output Data (D4_DR) Input Data 1 (D4_DR) → Stage 1 → Stage 2 → Stage 3 → Output Data (D4_DR)	D4_DR, D3_DM



NOTE 4. Usage of Data Pins

COM / SEG (CS pin)	Application mode (AMS pin)	SHL	Data interface pin			
			D1_SID	D2_DL	D3_DM	D4_DR
SEG (CS ="Low")	4-bit parallel interface mode (AMS = "Low")	X	D1 (input)	D2 (input2)	D3 (input3)	D4 (input4)
	1-bit serial interface mode (AMS = "High")	X	SID (input)	Connect to VDD		
COM (CS = "High")	single-type application mode (AMS = "Low")	L	open	DL (input)	Open	DR (output)
		H		DL (output)		DR (input)
	dual-type application mode (AMS = "High")	L	open	DL (input1)	DM (input2)	DR (output2)
		H		DL (output2)	DM (input2)	DR (input1)

3、ELECTRICAL PARAMETER

3.1、ABSOLUTE MAXIMUM RATINGS

(Tamb=25°C, All voltage referenced to Vss, unless otherwise specified)

Characteristic	Symbol	Conditions	Value	Unit
Power supply voltage	V _{DD}		-0.3 – +7.0	V
Driver supply voltage	V _{LCD}		0 – +25	V
Input voltage	V _{IN}		-0.3 – V _{DD} + 0.3	V
Operating temperature	T _{opr}		-30 – +85	°C
Storage temperature	T _{stg}		-55 – +150	°C
Soldering Temperature	T _L	10s	245	°C

* NOTE: Voltage greater than above may do damage to the circuit.

3.2、ELECTRICAL CHARACTERISTICS

3.2.1、DC CHARACTERISTICS

(1) Segment Driver Application (V_{SS} = 0V, Ta = - 30 – +85°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Operating Voltage1	V _{DD}	-	2.7	-	5.5	V
	V _{LCD}	V _{IN} = V _{DD} - V _{EE}	6	-	23	
Input voltage (1)	V _{IH}	-	0.8V _{DD}	-	V _{DD}	
	V _{IL}	-	0	-	0.2V _{DD}	
Output voltage (2)	V _{OH}	I _{OH} = -0.4mA	V _{DD} -0.4	-	-	V
	V _{OL}	I _{OL} = 0.4mA	-	-	0.4	



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Input leakage current 1 (1)	I_{IL1}	$V_{IN} = V_{DD} \text{to } V_{SS}$		-10	-	10	μA
Input leakage current 2 (3)	I_{IL2}	$V_{IN} = V_{DD} \text{to } V_{EE}$		-25	-	25	
On resistance (4)	R_{ON}	$I_{ON} = 100\mu A$		-	2	4	$k\Omega$
Supply current (5)	I_{STBY}	$f_{CL1} = 32\text{kHz} M = V_{SS}$	V_{SSPIN}	-	-	100	μA
	I_{DD}	$f_{CL1} = 32\text{kHz } f_M = 80\text{Hz}$	$V_{DD} = 5V$	-	-	5	mA
			$V_{DD} = 3V$	-	-	2	
	I_{EE}		$V_{DD} = 5V$	-	-	500	μA

NOTES:

1. Applied to CL1, CL2, ELB, ERB, D1_SID - D4_DR, SHL, DISPOFFB, M, CS, AMS pin
 2. ELB, ERB pin
 3. V0, V12, V43, V5 pin
 4. VLCD = VDD - VEE, V0 = VDD = 5V, V5 = VEE = -23 V
 $V_{12} = VDD - n(VLCD)$, $V_{43} = VEE + 2/n(VLCD)$, $n = 17$ (1/256 duty, 1/17 bias)
 5. V0 = VDD, $V_{12} = 1.71V$ (VDD = 5V) or -0.06V (VDD = 3V),
 $V_{43} = -19.71V$ (VDD = 5V) or -19.94V (VDD = 3V), $V5 = VEE = -23V$, no-load condition (1/256 duty, 1/17 bias)
- 4-bit parallel interface mode
- ISTBY : VDD = 5V, fCL2 = 5.12MHz, SHL = VSS, DISPOFFB = VDD,
M = VSS, display data pattern = 0000
- IDD : VDD = 3V, fCL2 = 4MHz, display data pattern = 0101
- VDD = 5 V, fCL2 = 5.12MHz, display data pattern = 0101
- IEE : VDD = 5V, fCL2 = 5.12MHz, display data pattern = 0101, VEE pin

(2) Common Driver Application ($V_{SS} = 0V$, $T_a = -30 - +85^\circ C$)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Operating voltage	V_{DD}	-	2.7	-	5.5	V
	V_{LCD}	$V_{IN} = V_{DD} - V_{EE}$	6	-	23	
Input voltage (1)	V_{IH}	-	$0.8V_{DD}$	-	V_{DD}	V
	V_{IL}	-	0	-	$0.2V_{DD}$	
Output voltage (3)	V_{OH}	$I_{OH} = -0.4mA$	$V_{DD} - 0.4$	-	-	V
	V_{OL}	$I_{OL} = 0.4mA$	-	-	0.4	
Input leakage current 1 (1)	I_{IL1}	$V_{IN} = V_{DD} \text{to } V_{SS}$	-10	-	10	μA
Input leakage current 2 (2)	I_{IL2}	$V_{IN} = 0V, V_{DD} = 5V$ (PULL UP)	-50	-125	-250	



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Input leakage current 3 (4)	I_{IL3}	V_{IN} = V_{DD} to V_{EE}		-25	-	25	
On resistance(5)	R_{ON}	I_{ON} = 100μA		-	2	4	kΩ
Supply current (6)	I_{STBY}	f_{CL1} = 32kHz	V_{SSPIN}	-	-	100	μA
	I_{DD}	f_{CL1} = 32kHz f_M = 80Hz	V_{DD} = 5V	-	-	200	
			V_{DD} = 3V	-	-	120	
	I_{EE}		V_{DD} = 5V	-	-	150	

NOTES:

- Applied to CL1, D2_DL (SHL = LOW), D4_DR (SHL = HIGH), SHL, DISPOFFB, M, CS, AMS pin
- Pull-up input pins : CL2, D1_SID, D3_DM (AMS = HIGH), ELB (SHL = LOW), ERB (SHL = HIGH)
- D2_DL (SHL = HIGH) , D4_DR (SHL = LOW) pin
- V0, V12, V43, V5 pin
- VLCD = VDD-VEE, V0 = VDD = 5V, V5 = VEE = -23V
V12 = VDD-1/n(VLCD), V43 = VEE+1/n(VLCD), n = 17(1/256 duty, 1/17 bias)
- V0 = VDD, V12 = 3.35V (VDD = 5V) or 1.47V (VDD = 3V),
V43 = -21.35V (VDD = 5 V) or -21.47V (VDD = 3 V), V5 = VEE = -23 V, no-load condition (1/256 duty, 1/17 bias)
single-type mode operation : AMS = VSS, SHL = VSS, DISPOFFB = VDD
D1_SID = D3_DM = VDD, D4_DR = OPEN, ELB = ERB = OPEN,
ISTBY : VDD = 5V, M = VSS, D2_DL = VSS
IDD : fM = 80Hz, D2_DL = VDD
VDD = 3 V, display data pattern = 10000000..., 01000000..., 00100000..., 00010000..., ..
VDD = 5 V, display data pattern = 10000000..., 01000000..., 00100000..., 00010000..., ..
IEE : fM = 80Hz, D2_DL = VDD
VDD = 5V, current through VEE Pin,
display data pattern = 10000000..., 01000000..., 00100000..., 00010000...

3.2.2、AC CHARACTERISTICS

(1) Segment Driver Application (VSS = 0V, Ta = - 30 – +85°C)

Characteristic	Symbol	Test Condition	(1) V _{DD} = 5V 10%			(2) V _{DD} = 3V 10%			Unit
			Min.	Typ.	Max	Min.	Typ.	Max.	
Clock cycle time	t _{CY}	Duty = 50%	125	-	-	250	-	-	ns
Clock pulse width	t _{WCK}	-	45	-	-	95	-	-	
Clock rise / fall time	t _{R/F}	-	-	-	-	-	-	30	
Data set-up time	t _{DS}	-	30	-	-	65	-	-	
Data hold time	t _{DH}	-	30	-	-	65	-	-	
Clock set-up time	t _{CS}	-	80	-	-	120	-	-	
Clock hold time	t _{CH}	-	80	-	-	120	-	-	
Propagation delay time	t _{PHL}	ELB Output	-	-	60	-	-	125	
		ERB Output	-	-	60	-	-	125	



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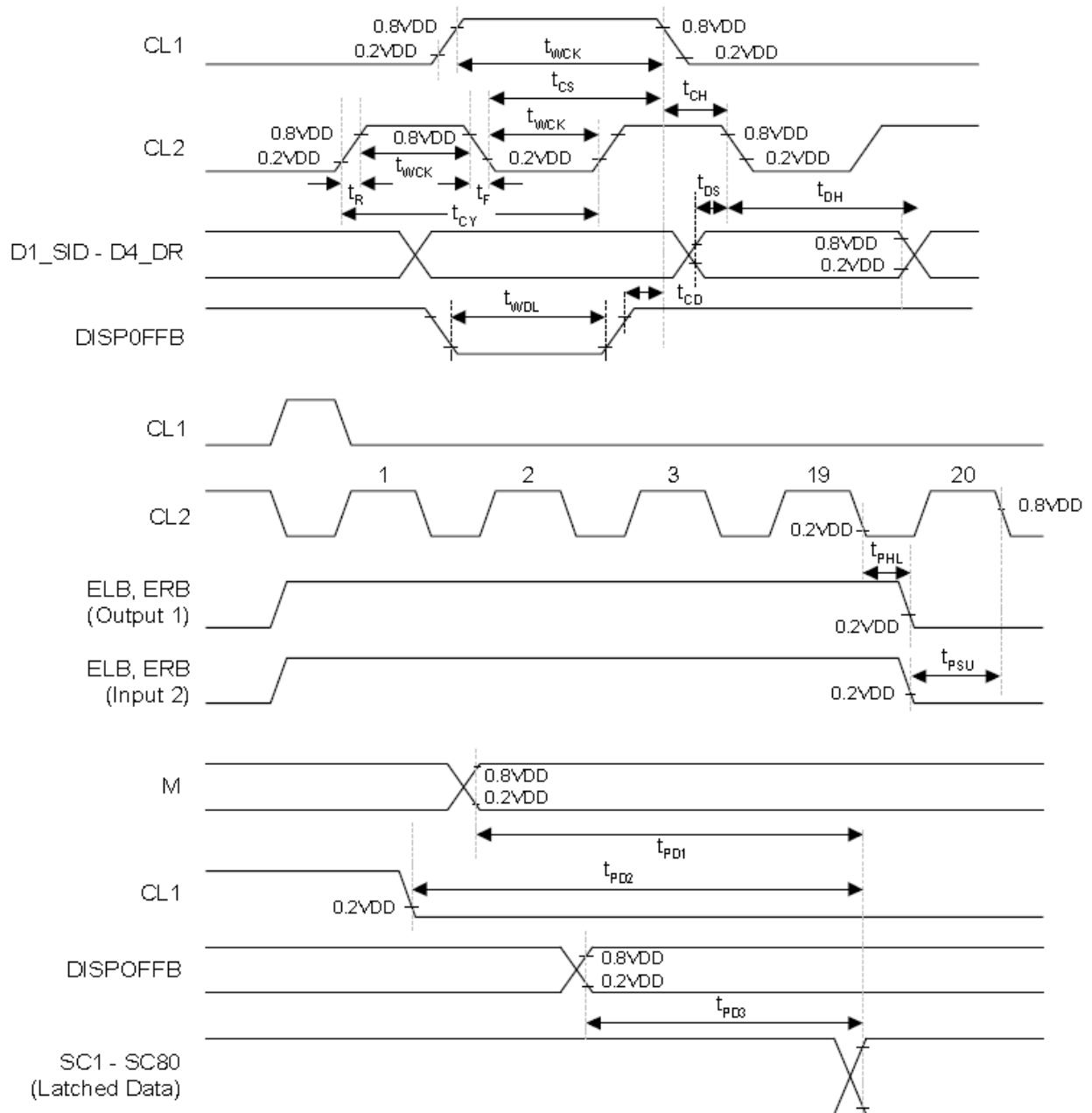
ELB,ERB set-up time	tPSU	ELB Input	30	-	-	65	-	-	
		ERB Input	30	-	-	65	-	-	
DISPOFFB low pulse width	t _{WDL}	-	1.2	-	-	1.2	-	-	s
DISPOFFB clear time	t _{CD}	-	100	-	-	100	-	-	ns
M - OUT propagation delay time	t _{PD1}	CL = 15pF	-	-	1.0	-	-	1.2	μs
CL1 - OUT propagation delay time	t _{PD2}		-	-	1.0	-	-	1.2	
DISPOFFB - OUT propagation delay time	t _{PD3}		-	-	1.0	-	-	1.2	

(2) Common Driver Application (V_{SS} = 0V, Ta = - 30 – +85°C)

Characteristic	Symbol	Test Condition	(1) V _{DD} = 5V 10%			(2) V _{DD} = 3V 10%			Unit
			Min.	Typ.	Max	Min.	Typ	Max.	
Clock cycle time	t _{CY}	Duty = 50%	250	-	-	500	-	-	ns
Clock pulse width	t _{WCK}	-	45	-	-	95	-	-	
Clock rise / fall time	t _{R/F}	-	-	-	50	-	-	50	
Data set-up time	t _{DS}	-	30	-	-	65	-	-	
Data hold time	t _{DH}	-	30	-	-	65	-	-	
DISPOFFB low pulse width	t _{WDL}	-	1.2	-	-	1.2	-	-	μs
DISPOFFB clear time	t _{CD}	-	100	-	-	100	-	-	ns
Output delay time	t _{DL}	CL = 15pF	-	-	200	-	-	250	ns
M - OUT propagation delay time	t _{PD1}		-	-	1.0	-	-	1.2	μs
CL1 - OUT propagation delay time	t _{PD2}		-	-	1.0	-	-	1.2	
DISPOFFB - OUT propagation delay time	t _{PD3}		-	-	1.0	-	-	1.2	

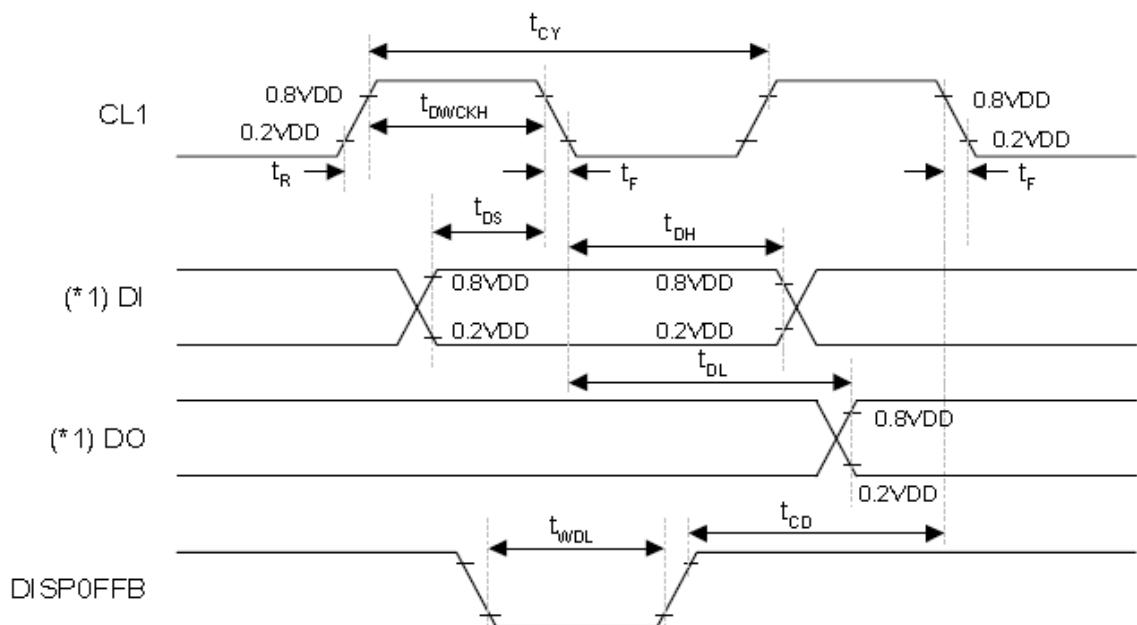


(3) Segment Driver Application Timing





(4) Common Driver Application Timing



(*1) When in single-type interface mode

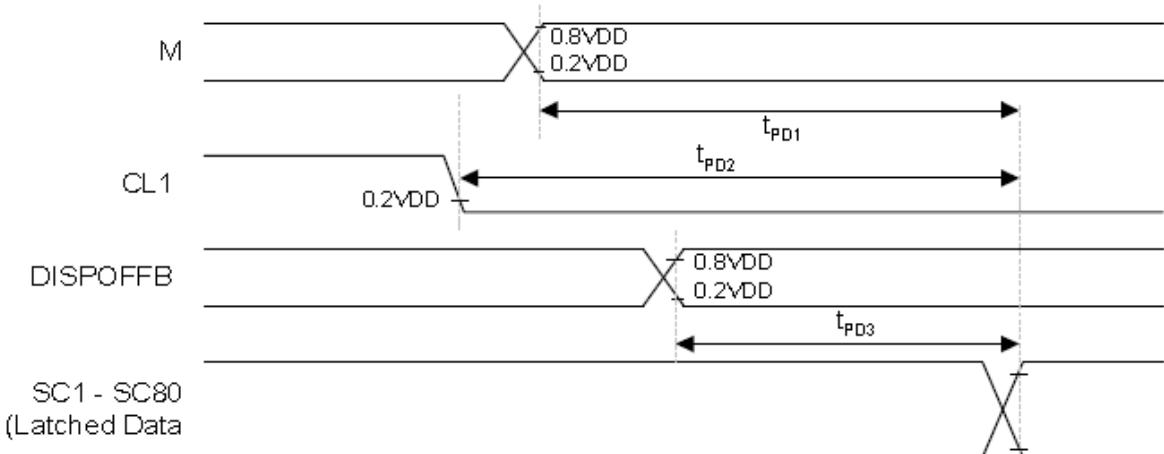
DI => D2_DL (SHL = L), D4_DR (SHL = H)

DO => D4_DR (SHL = L), D2_DL (SHL = H)

When in dual-type interface mode

DI => D2_DL and D3_DM (SHL = L), D4_DR and D3_DM (SHL = H)

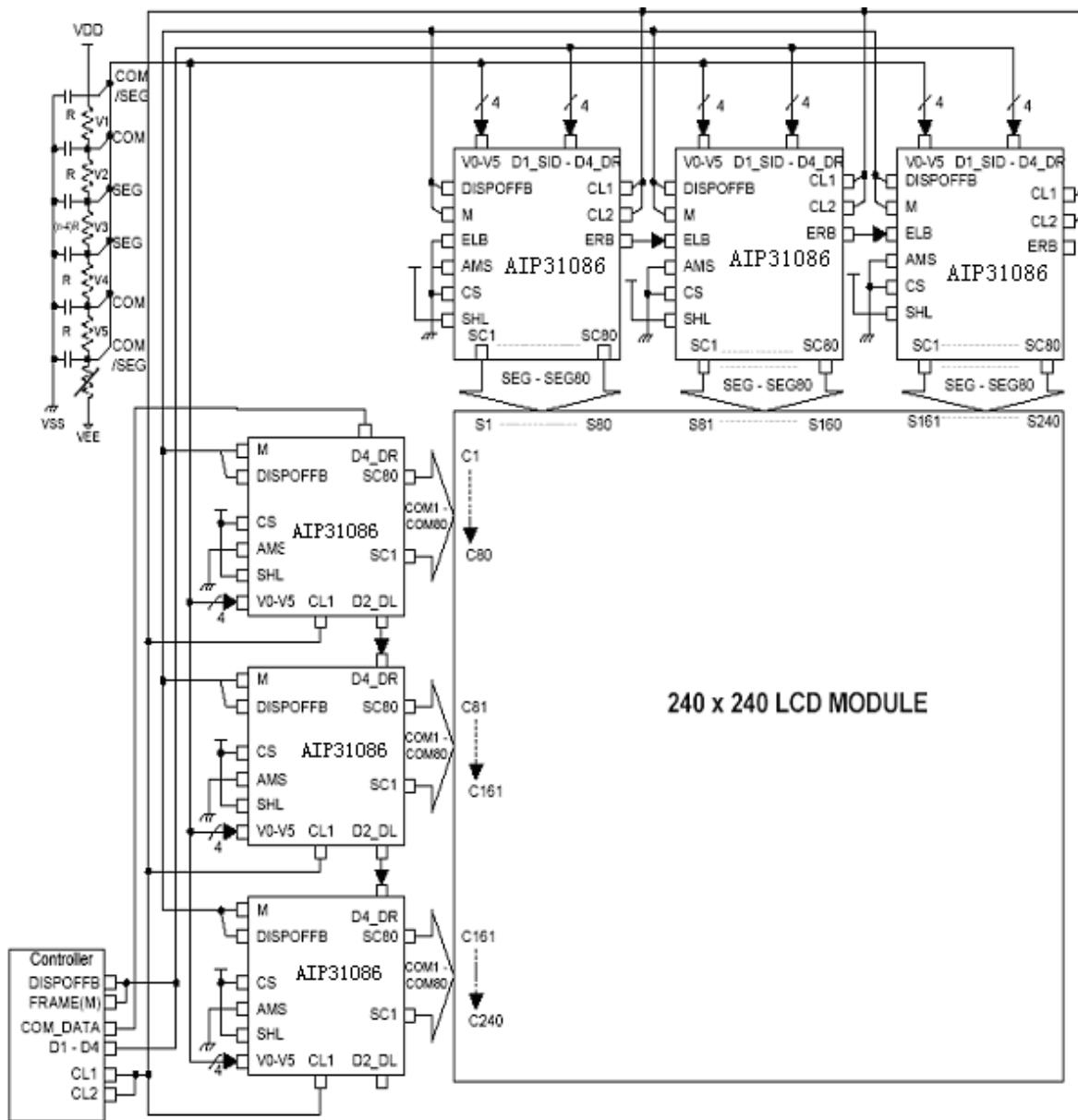
DO => D4_DR (SHL = L), D2_DL (SHL = H)





4. TYPICAL APPLICATION CIRCUIT AND FUNCTION DESCRIPTION

4.1. APPLICATION CIRCUIT





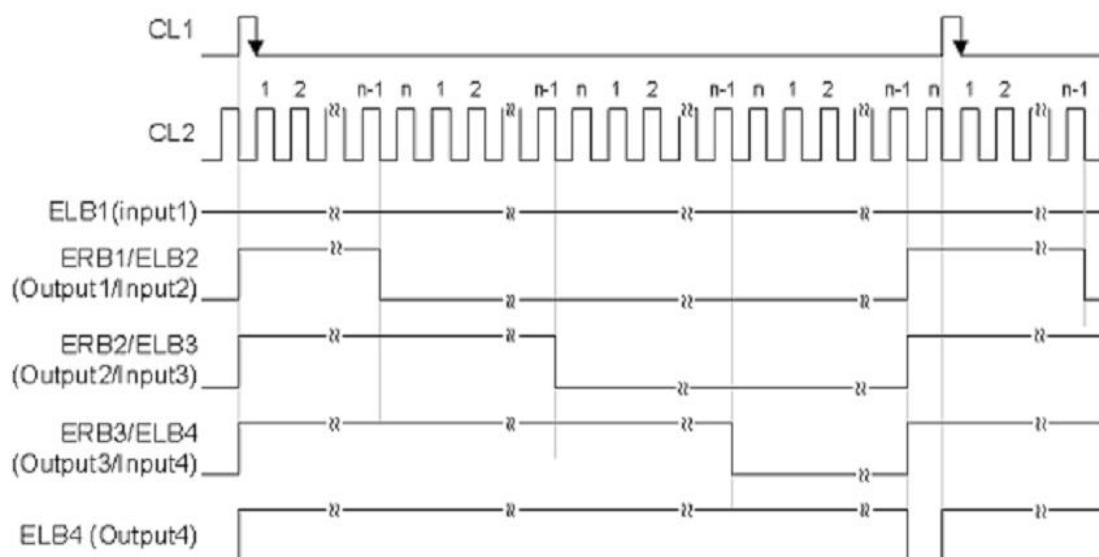
4.2、APPLICATION NOTE

POWER DOWN FUNCTION

In the case of cascade connection of segment mode drivers, AIP31086 has a "power down function" In order to reduce the power consumption.

SHL	Enable input	Enable output	Current driver status	The other drivers status
L	ERB	ELB	While ERB ="Low", current driver is enabled.	Disabled
H	ELB	ERB	While ELB ="Low", current driver is enabled.	Disabled

- In the case of common driver application, power down function does not work.



Notes:

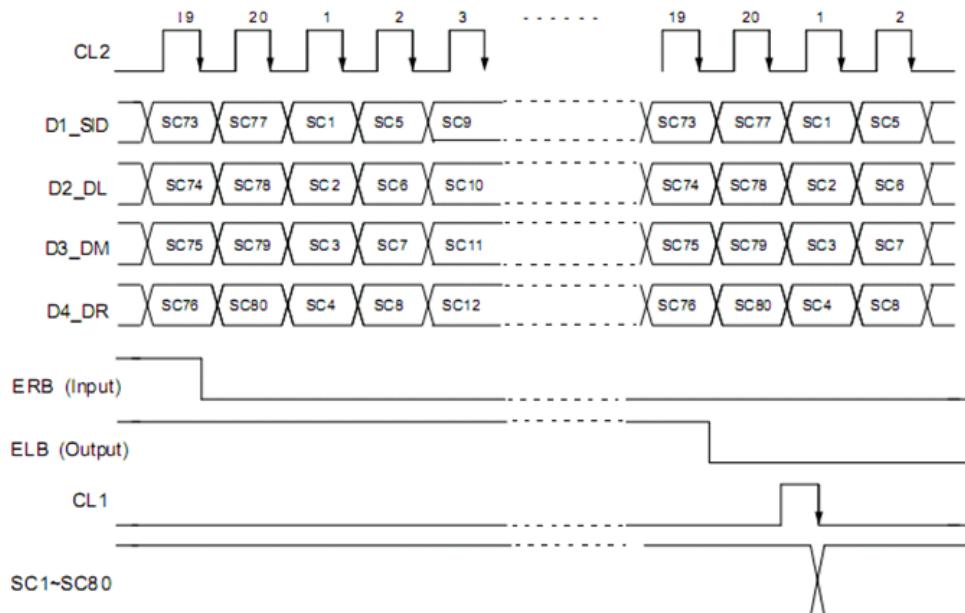
1. SHL=High (EBL=Input, ERB=Output)
Current AIP31086'S ERB must be connected to the next AIP31086'S ELB.
2. When in 4-bit parallel interface mode: n=20
When in 1-bit serial interface mode: n=80



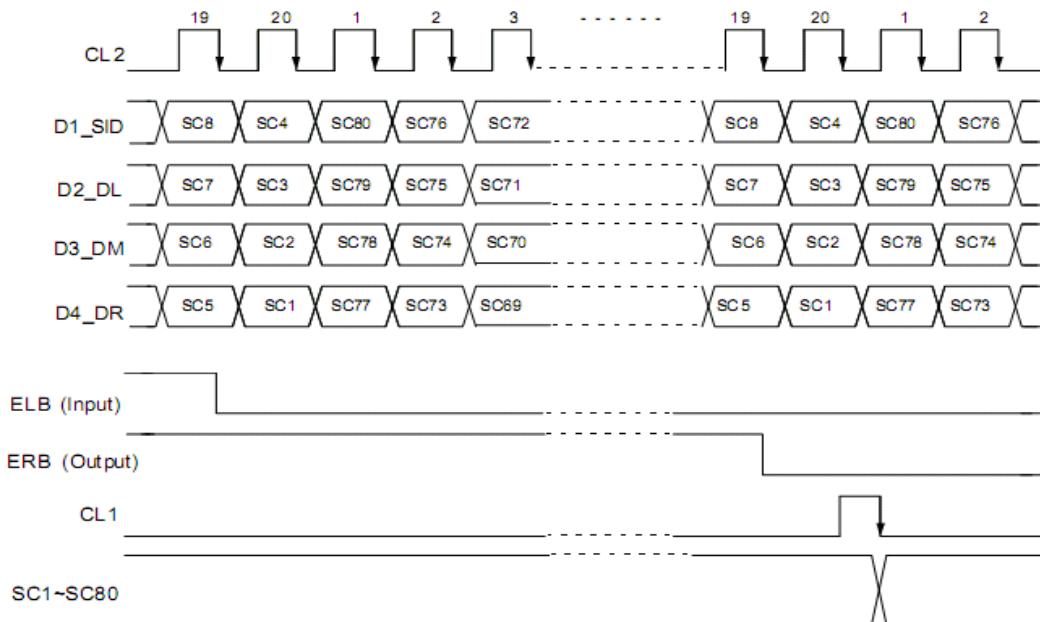
OPERATION TIMING DIAGRAM

(1) 4-bit Parallel Mode Interface Segment Driver

- When SHL = "Low"



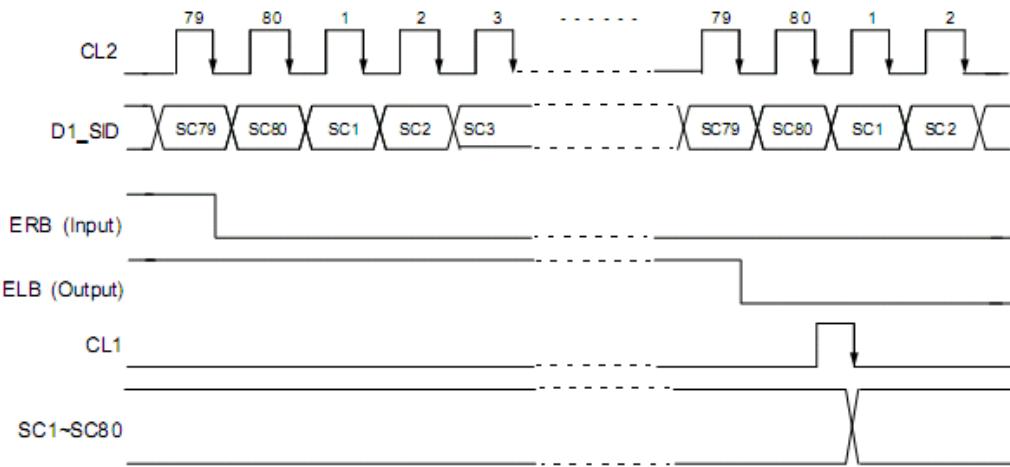
- When SHL = "High"



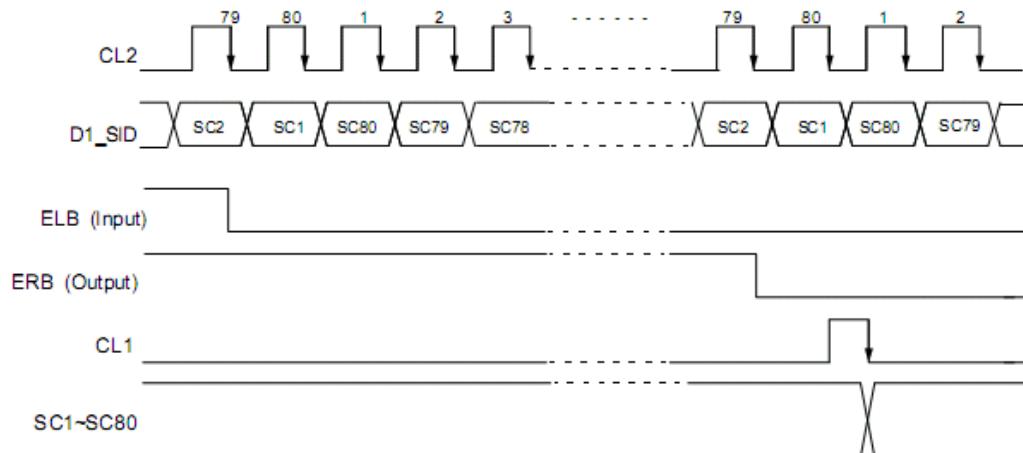


(2) 1-bit Serial Mode Interface Segment Driver

- When SHL = "Low"



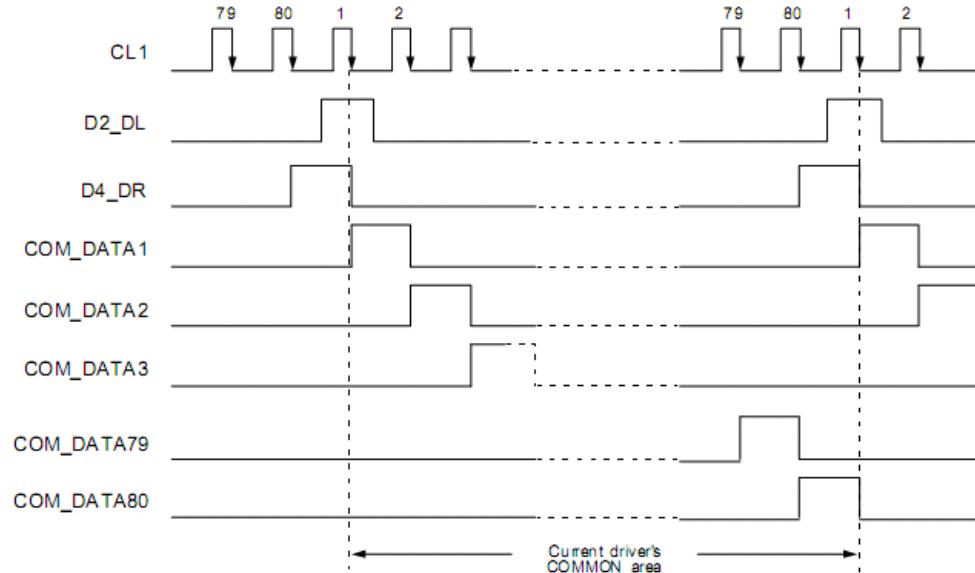
- When SHL = "High"



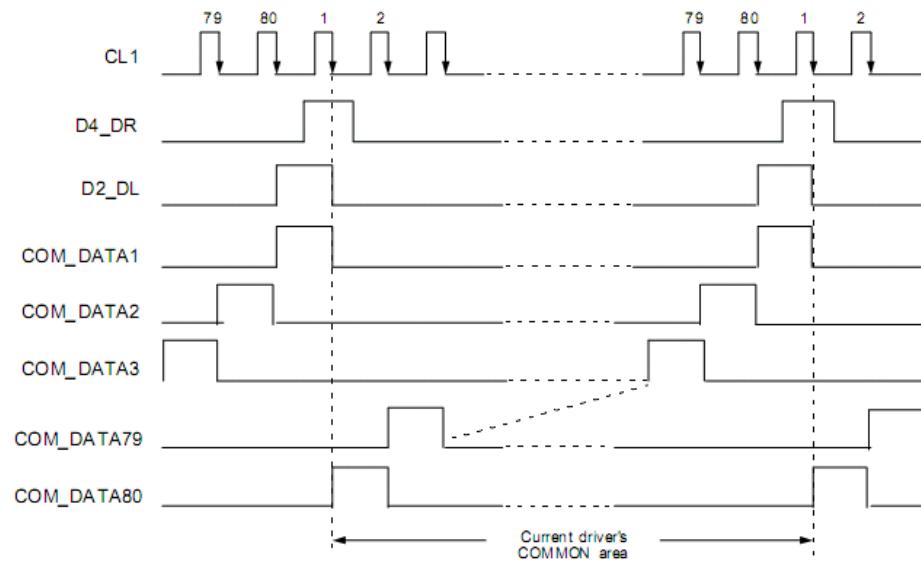


(3) Single-type Interface Mode Common Driver

- When SHL = "Low"



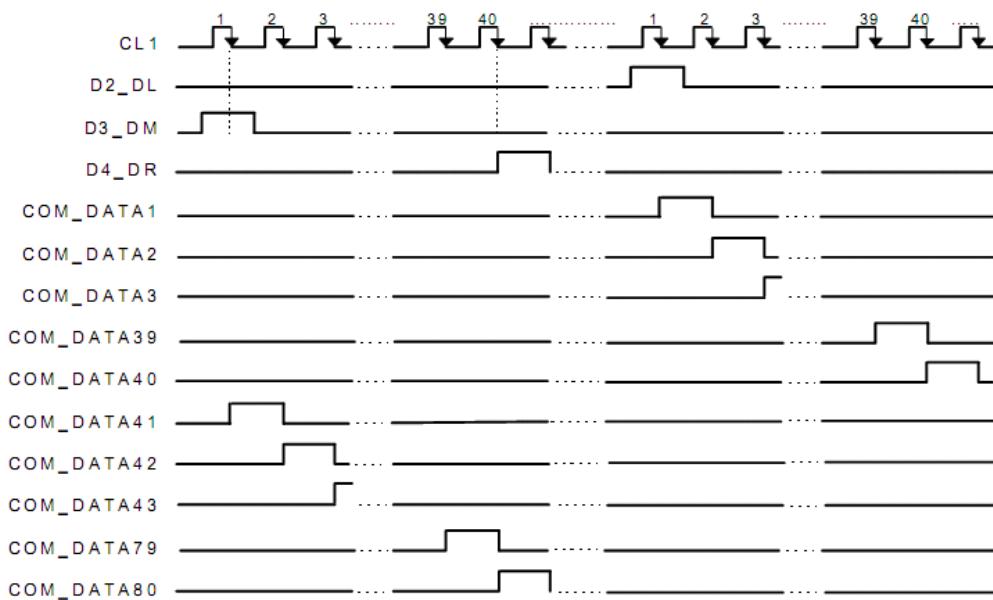
- When SHL = "High"



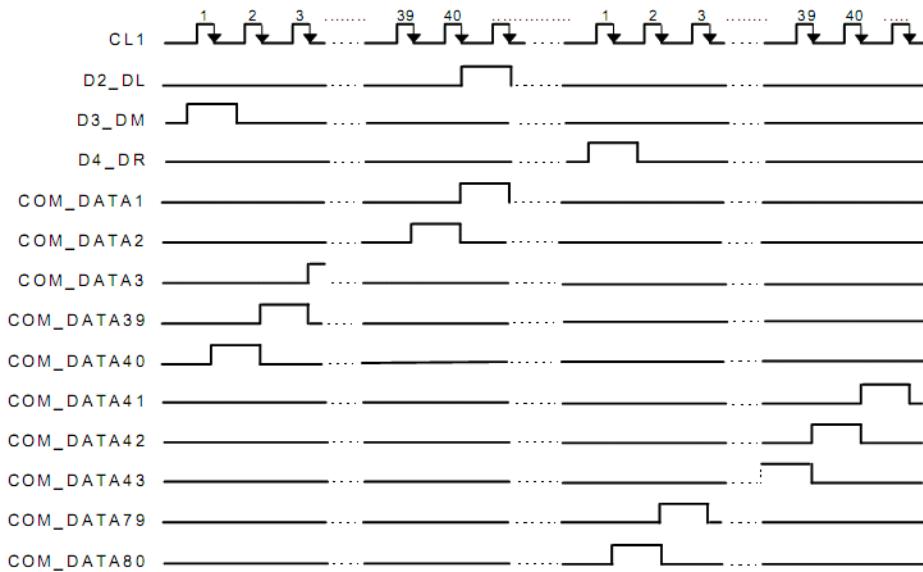


(4) DUAL-type Interface Mode Common Driver

- When SHL = "Low"

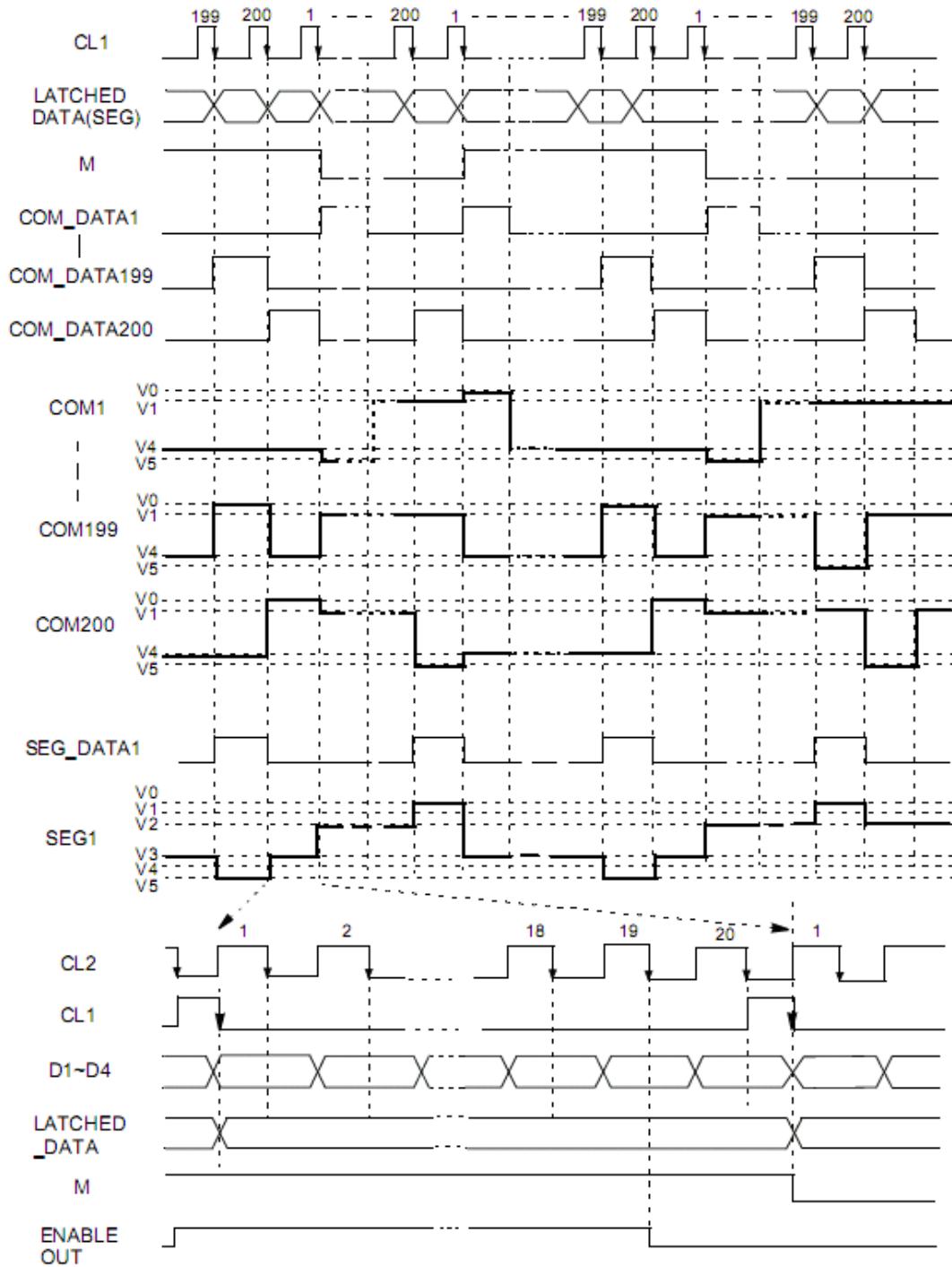


- When SHL = "High"





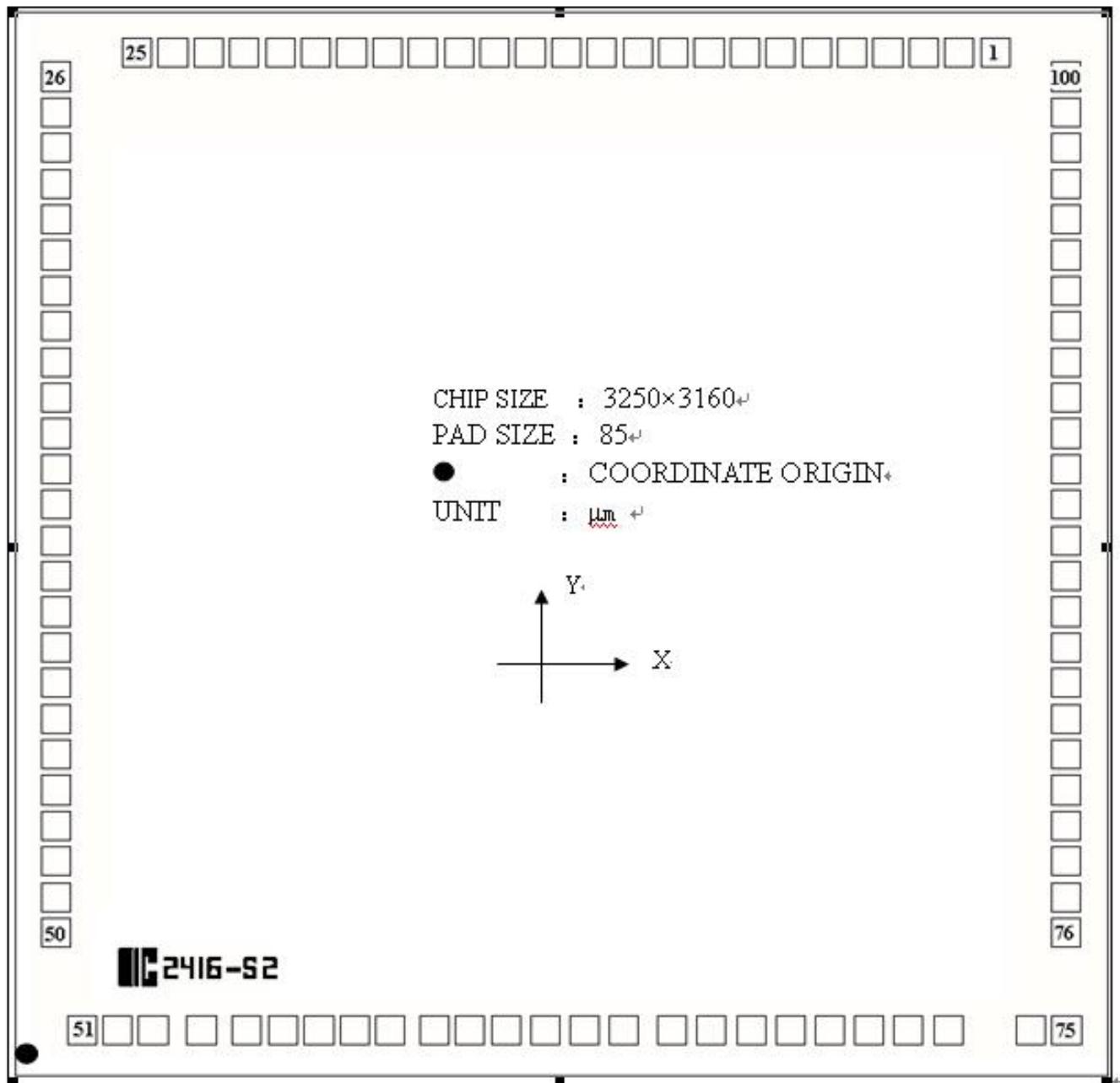
(5) Common / Segment Driver Timing (1/200 DUTY)





5、PAD DIAGRAM AND PAD LOCATION

5.1、PAD DIAGRAM





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5.2、PAD Location (UNIT: μm)

PAD No.	Pin Name	X	Y	PAD No.	Pin Name	X	Y
1	SC28	2859.95	2978.50	51	SC78	177.30	101.50
2	SC29	2754.95	2978.50	52	SC79	282.30	101.50
3	SC30	2649.95	2978.50	53	SC80	387.30	101.50
4	SC31	2544.95	2978.50	54	ERB	529.00	101.50
5	SC32	2439.95	2978.50	55	VEE	659.90	101.50
6	SC33	2334.95	2978.50	56	V5	768.90	101.50
7	SC34	2229.95	2978.50	57	V43	873.90	101.50
8	SC35	2124.95	2978.50	58	V12	978.90	101.50
9	SC36	2019.95	2978.50	59	V0	1083.90	101.50
10	SC37	1914.95	2978.50	60	CS	1212.55	101.50
11	SC38	1809.95	2978.50	61	M	1317.55	101.50
12	SC39	1704.95	2978.50	62	DISPOFFB	1422.55	101.50
13	SC40	1599.95	2978.50	63	VDD	1539.60	101.50
14	SC41	1494.95	2978.50	64	SHL	1654.65	101.50
15	SC42	1389.95	2978.50	65	GND	1769.65	101.50
16	SC43	1284.95	2978.50	66	D4	1910.20	101.50
17	SC44	1179.95	2978.50	67	D3	2025.20	101.50
18	SC45	1074.95	2978.50	68	D2	2145.20	101.50
19	SC46	969.95	2978.50	69	D1	2260.50	101.50
20	SC47	864.95	2978.50	70	CL2	2375.20	101.50
21	SC48	759.95	2978.50	71	AMS	2490.20	101.50
22	SC49	654.95	2978.50	72	CL1	2605.20	101.50
23	SC50	549.95	2978.50	73	ELB	2722.05	101.50
24	SC51	444.95	2978.50	74	SC1	2964.90	101.50
25	SC52	339.95	2978.50	75	SC2	3069.90	101.50
26	SC53	101.50	2908.15	76	SC3	3068.50	388.15
27	SC54	101.50	2803.15	77	SC4	3068.50	493.15
28	SC55	101.50	2698.15	78	SC5	3068.50	598.15
29	SC56	101.50	2593.15	79	SC6	3068.50	703.15
30	SC57	101.50	2488.15	80	SC7	3068.50	808.15
31	SC58	101.50	2383.15	81	SC8	3068.50	913.15
32	SC59	101.50	2278.15	82	SC9	3068.50	1018.15
33	SC60	101.50	2173.15	83	SC10	3068.50	1123.15
34	SC61	101.50	2068.15	84	SC11	3068.50	1228.15
35	SC62	101.50	1963.15	85	SC12	3068.50	1333.15
36	SC63	101.50	1858.15	86	SC13	3068.50	1438.15
37	SC64	101.50	1753.15	87	SC14	3068.50	1543.15
38	SC65	101.50	1648.15	88	SC15	3068.50	1648.15
39	SC66	101.50	1543.15	89	SC16	3068.50	1753.15



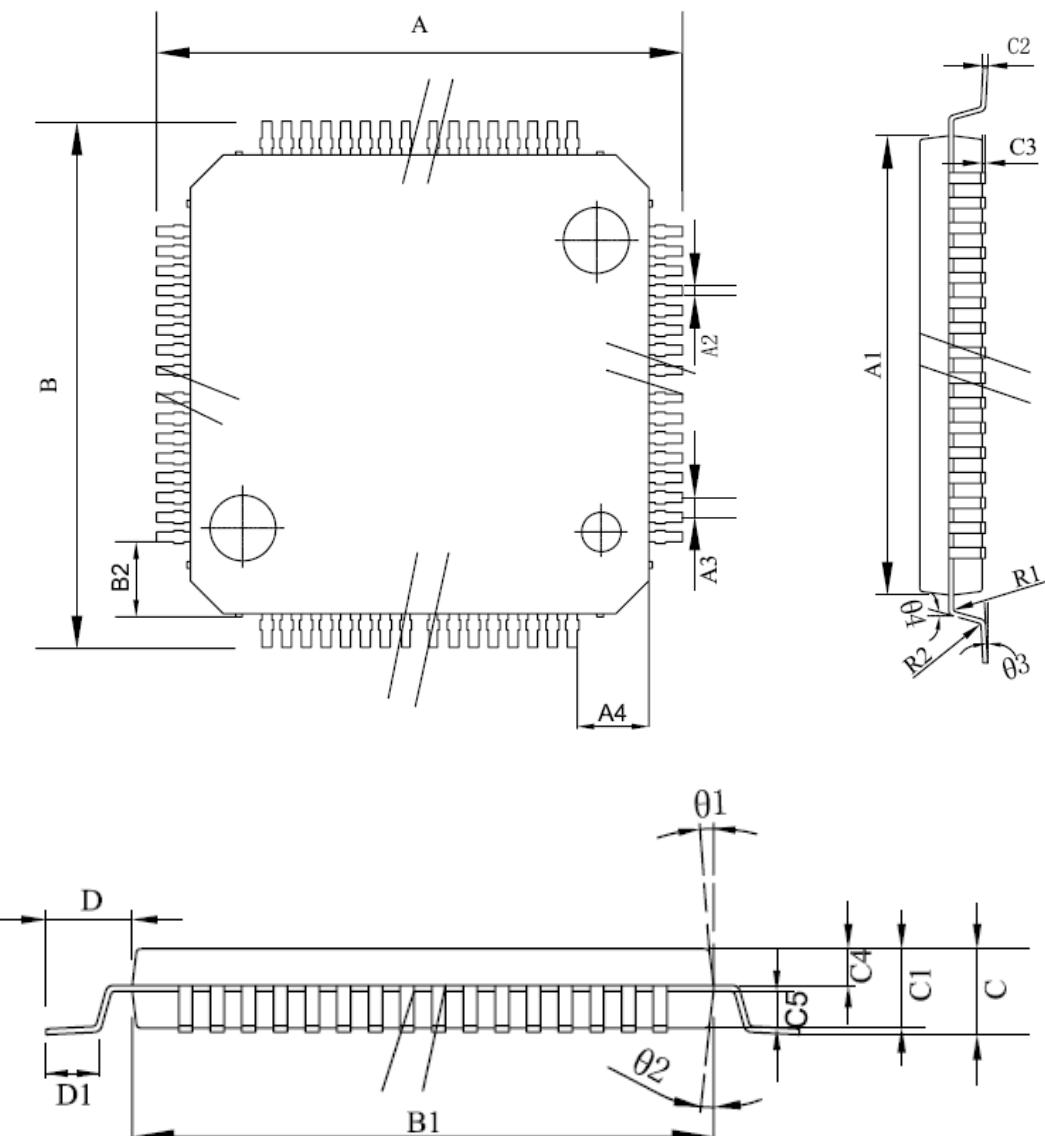
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40	SC67	101.50	1438.15	90	SC17	3068.50	1858.15
41	SC68	101.50	1333.15	91	SC18	3068.50	1963.15
42	SC69	101.50	1228.15	92	SC19	3068.50	2068.15
43	SC70	101.50	1123.15	93	SC20	3068.50	2173.15
44	SC71	101.50	1018.15	94	SC21	3068.50	2278.15
45	SC72	101.50	913.15	95	SC22	3068.50	2383.15
46	SC73	101.50	808.15	96	SC23	3068.50	2488.15
47	SC74	101.50	703.15	97	SC24	3068.50	2593.15
48	SC75	101.50	598.15	98	SC25	3068.50	2698.15
49	SC76	101.50	493.15	99	SC26	3068.50	2803.15
50	SC77	101.50	388.15	100	SC27	3068.50	2908.15



6、PACKAGE INFORMATION

6.1、LQFP100



尺寸 标注	最小 (mm)	最大 (mm)	尺寸 标注	最小 (mm)	最大 (mm)
A	15.80	16.20	C3	0.05	0.15
A1	13.90	14.10	C4	0.6365TYP	
A2	0.17	0.27	C5	0.6365TYP	
A3	0.5TYP		D	0.90	1.10
A4	0.9TYP		D1	0.45	0.70
B	15.80	16.20	R1	0.15TYP	
B1	13.90	14.10	R2	0.15TYP	
B2	0.9TYP		θ1	12° TYP	
C	1.40	1.60	θ2	12° TYP	
C1	1.35	1.45	θ3	4° TYP	
C2	0.09	0.18	θ4	4° TYP	



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7、STATEMENTS AND NOTES:

7.1、The name and content of Hazardous substances or Elements in the product

Part name	Hazardous substances or Elements					
	Lead and lead compounds	Mercury and mercury compounds	Cadmium and cadmium compounds	Hexavalent chromium compounds	Polybrominated biphenyls	Polybrominated biphenyl ethers
Lead frame	○	○	○	○	○	○
Plastic resin	○	○	○	○	○	○
Chip	○	○	○	○	○	○
The lead	○	○	○	○	○	○
Plastic sheet installed	○	○	○	○	○	○
explanation	<p>○: Indicates that the content of hazardous substances or elements in the detection limit of the following the SJ/T11363-2006 standard.</p> <p>×: Indicates that the content of hazardous substances or elements exceeding the SJ/T11363-2006 Standard limit requirements.</p>					

7.2 NOTION:

Recommended carefully reading this information before the use of this product;

The information in this document are subject to change without notice;

This information is using to the reference only, the company is not responsible for any loss;

The company is not responsible for the any infringement of the third party patents or other rights of the responsibility.

8、CONTACT:

Wuxi I-CORE Electronics Co., Ltd.

Addr: 2F Building9, 100Di cui Road, LiYuan Development Zone, Wuxi, jiangsu, China <http://www.i-core.cn>

P.C: 214072 Tel: 0510-81888895 Fax: 0510-85572700

Marketing Department: 2F Building9, 100Di cui Road, LiYuan Development Zone, Wuxi, jiangsu, China

P.C: 214072 Tel: 0510-85572708 Fax: 0510-85887721

Shenzhen office: 26F Building12, xiangli garden hongli west Road, Shenzhen, Guangdong ,China

P.C: 518000 Tel: 0755-88370509 Fax: 0755-88370507

Guangzhou office: 901room-57,ledeGarden, leming fiest street,Guanghua Road, baiyun District,Guangzhou,China

Tel: 020-36743257 Fax: 020-36743257

Applied Technical Services:

Application Department:

2F Building9, 100Di cui Road, LiYuan Development Zone, Wuxi, jiangsu, China

P.C: 214072 Tel: 0510-85572715 Fax: 0510-85572700

26F Building12, xiangli garden hongli west Road, Shenzhen, Guangdong ,China

P.C: 518000 Tel: 0755-88370509 Fax: 0755-88370507